
System-Level Power Management Strategies for Integrated Platforms

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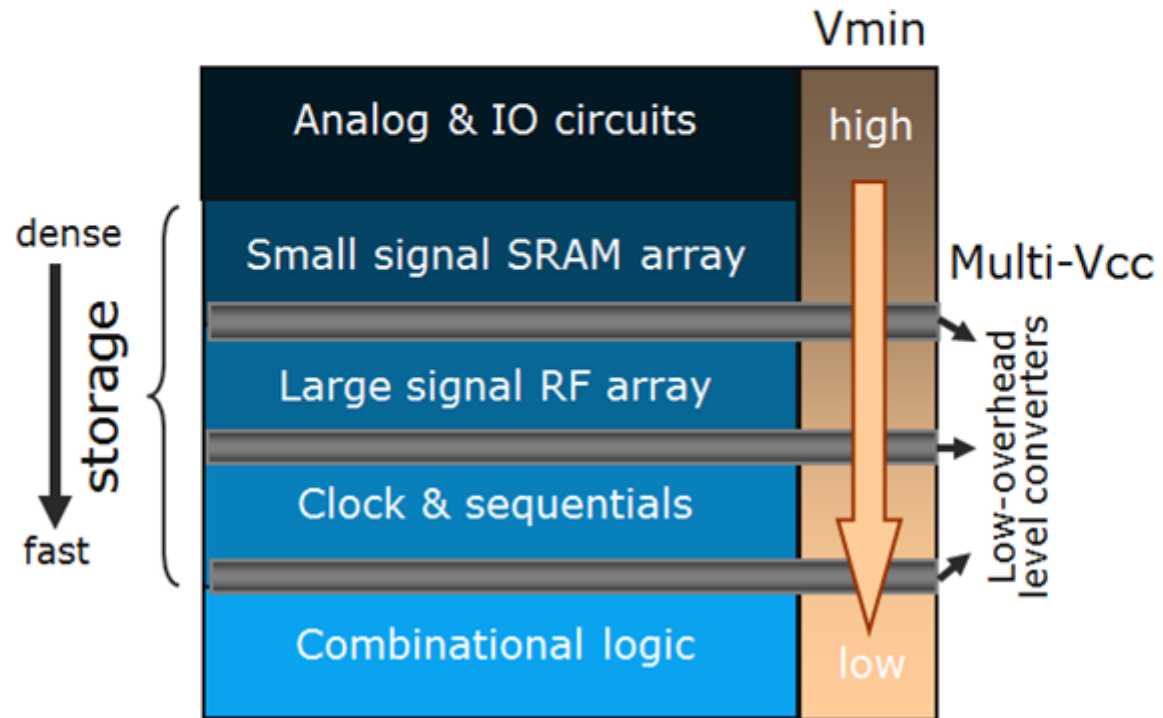
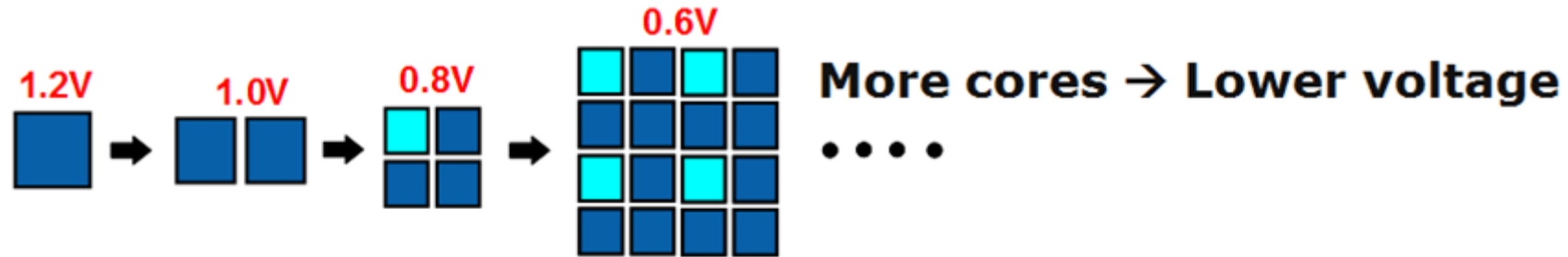
Internet of Everything



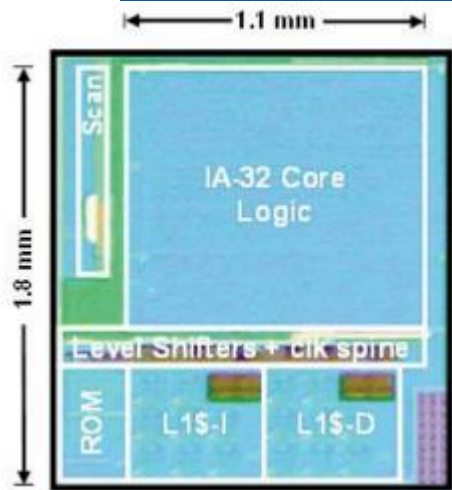
Cyberphysical systems with end-to-end energy efficiency

SoC Power Delivery & Management

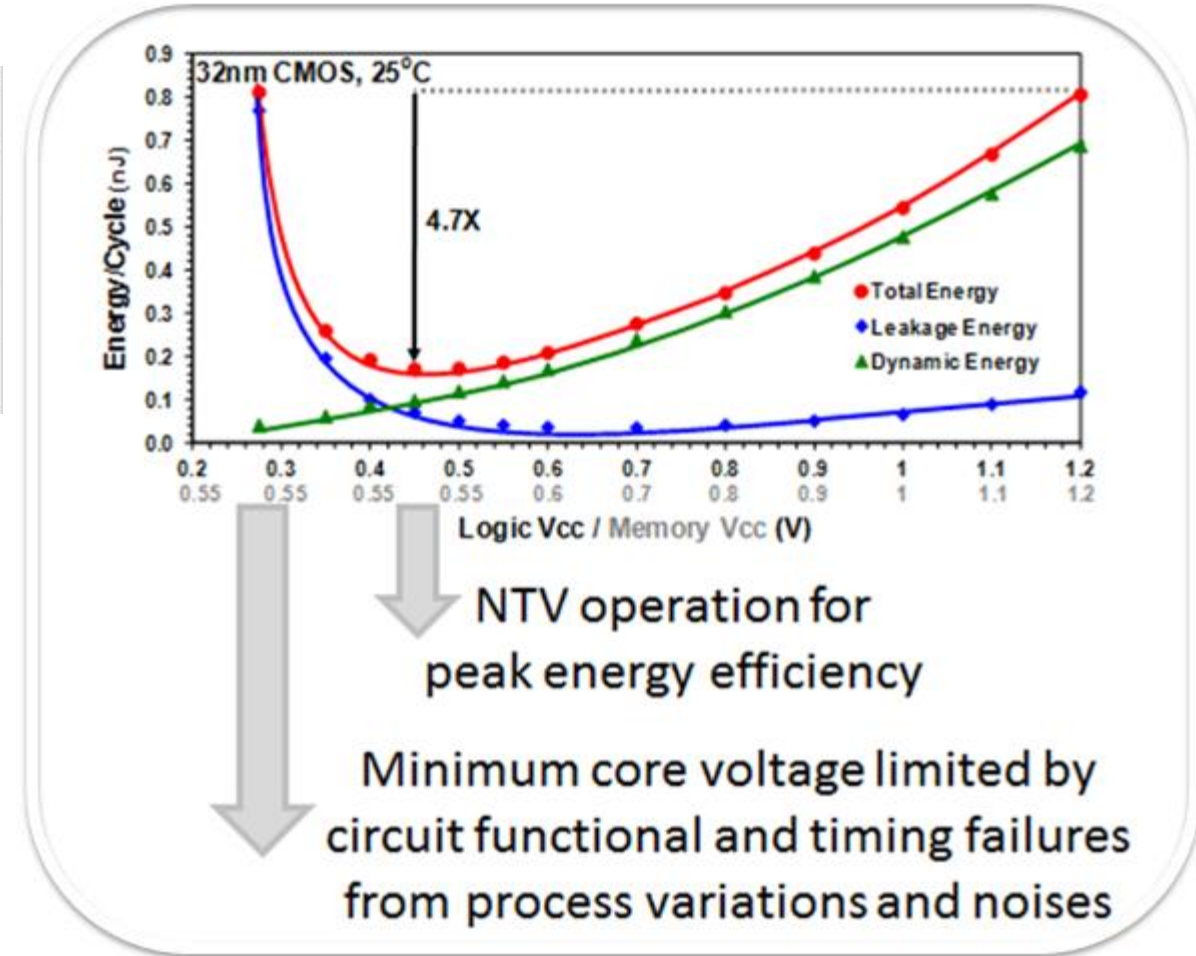
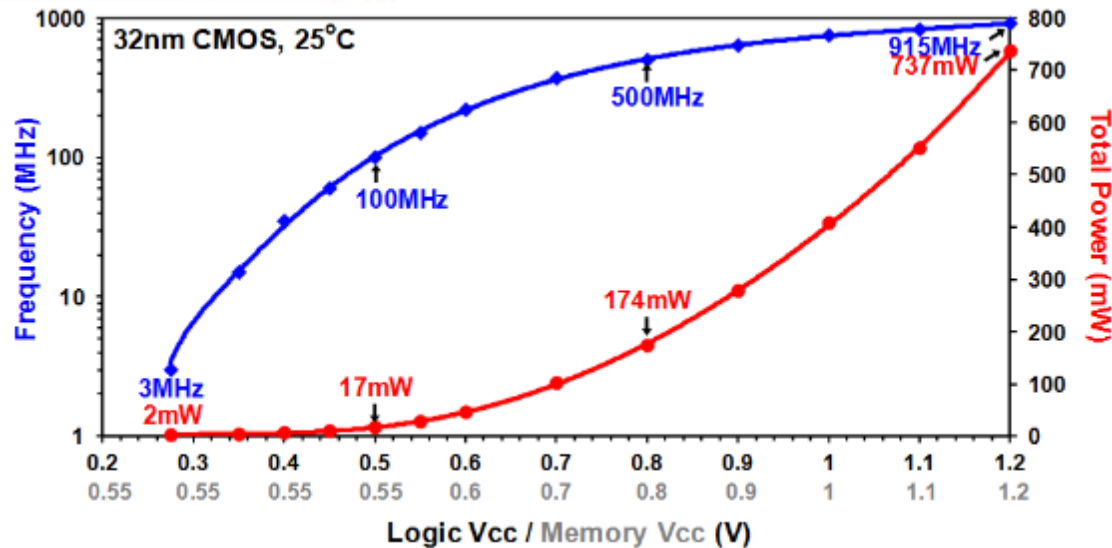
Fine-Grain Multi-Voltage SoC Design



Wide Range DVFS

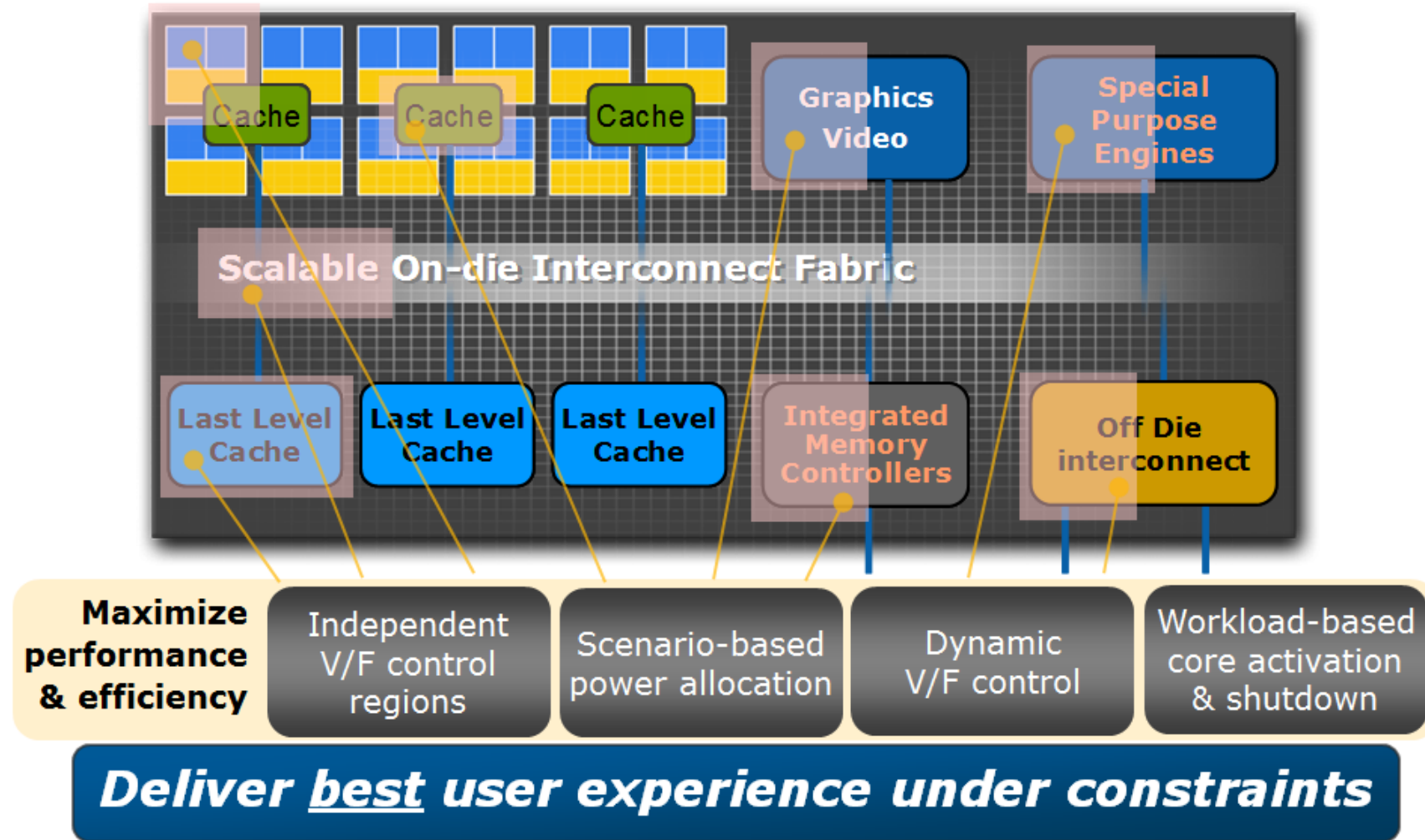


Technology	32nm High-K Metal Gate
Interconnect	1 Poly, 9 Metal (Cu)
Transistors	Core:6M
Core Area	2mm ²
Package	951 Pins FCBGA11

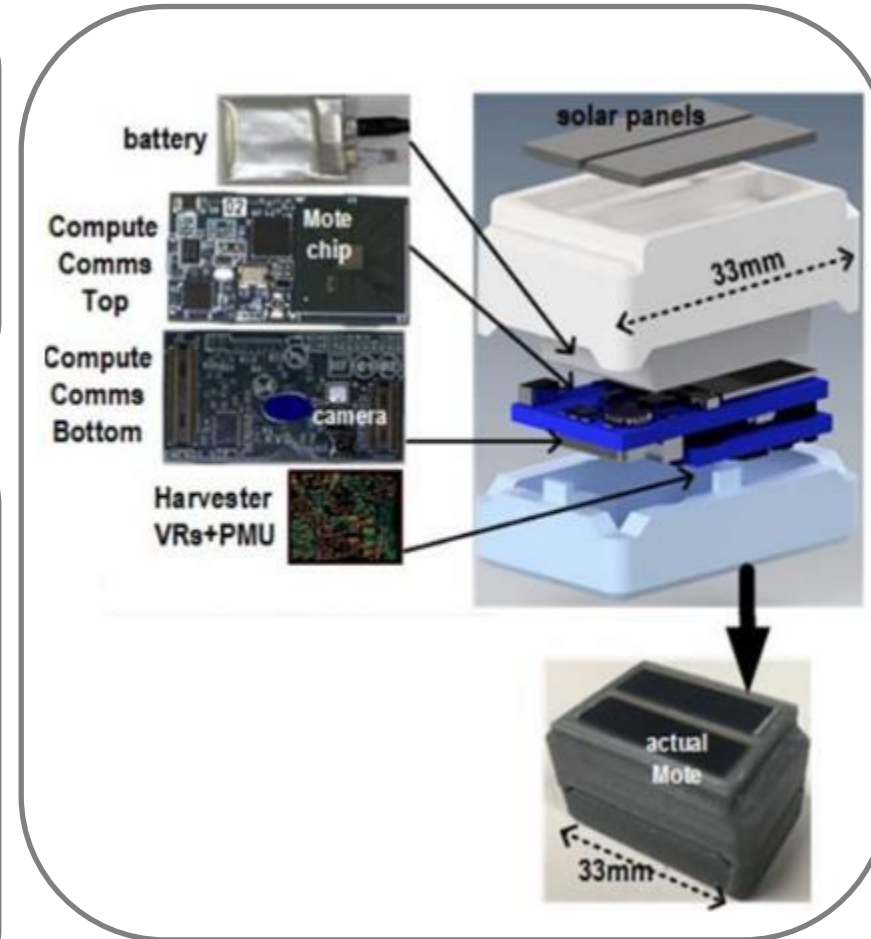
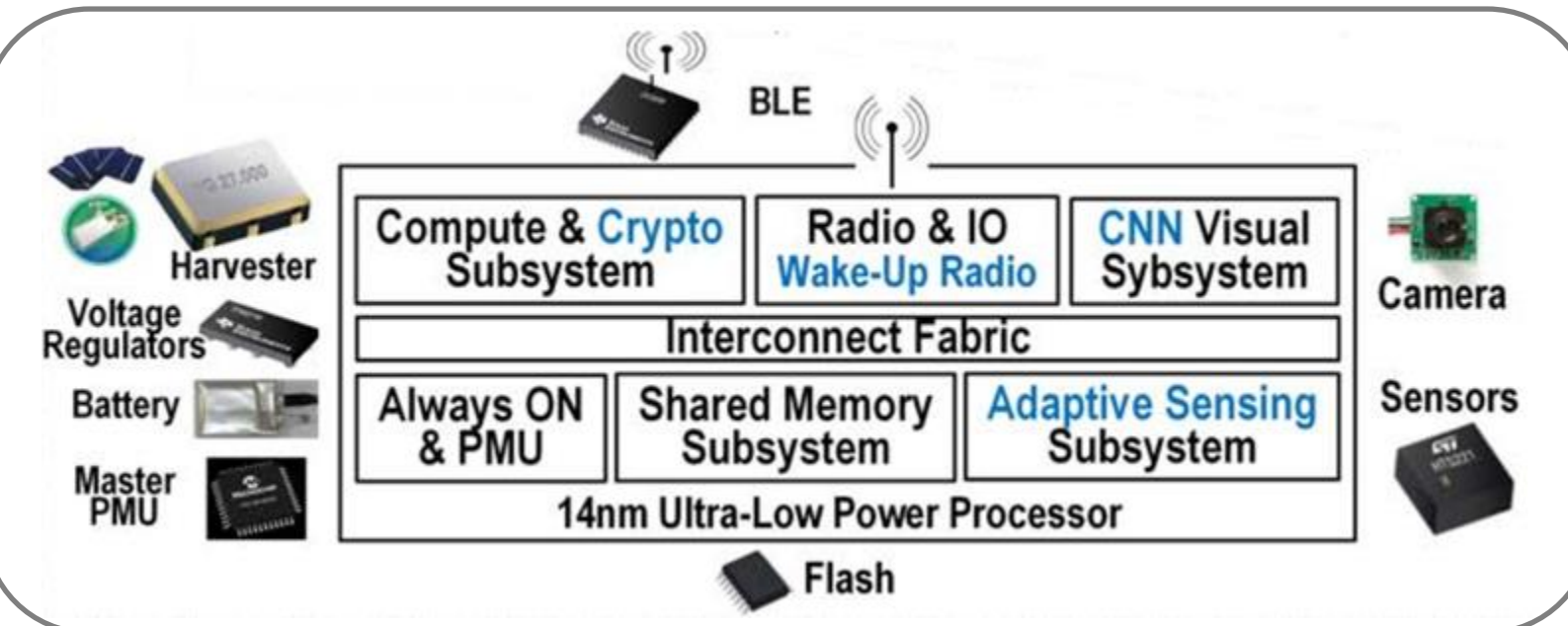
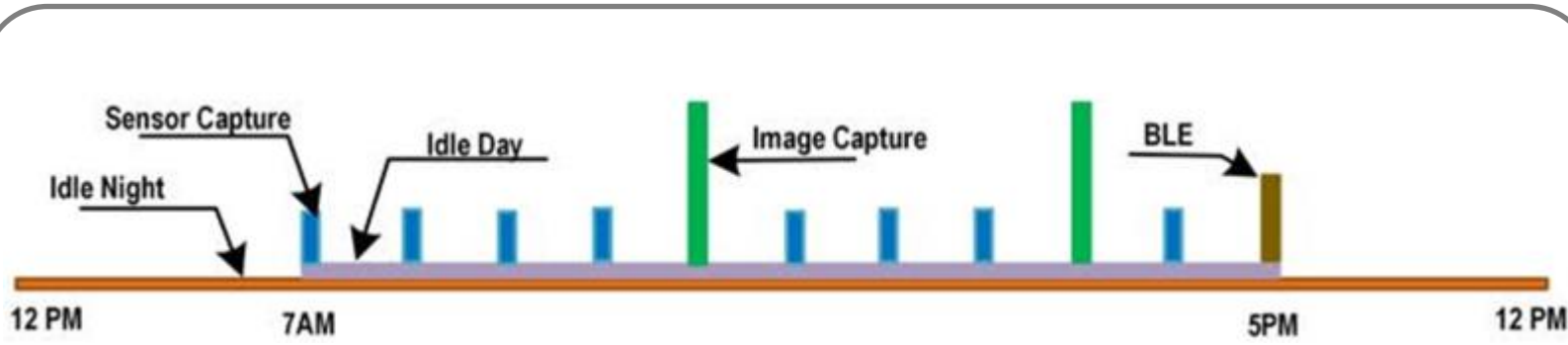


* S. Jain, et al., 2012 ISSCC

Fast & Efficient SoC Power Management

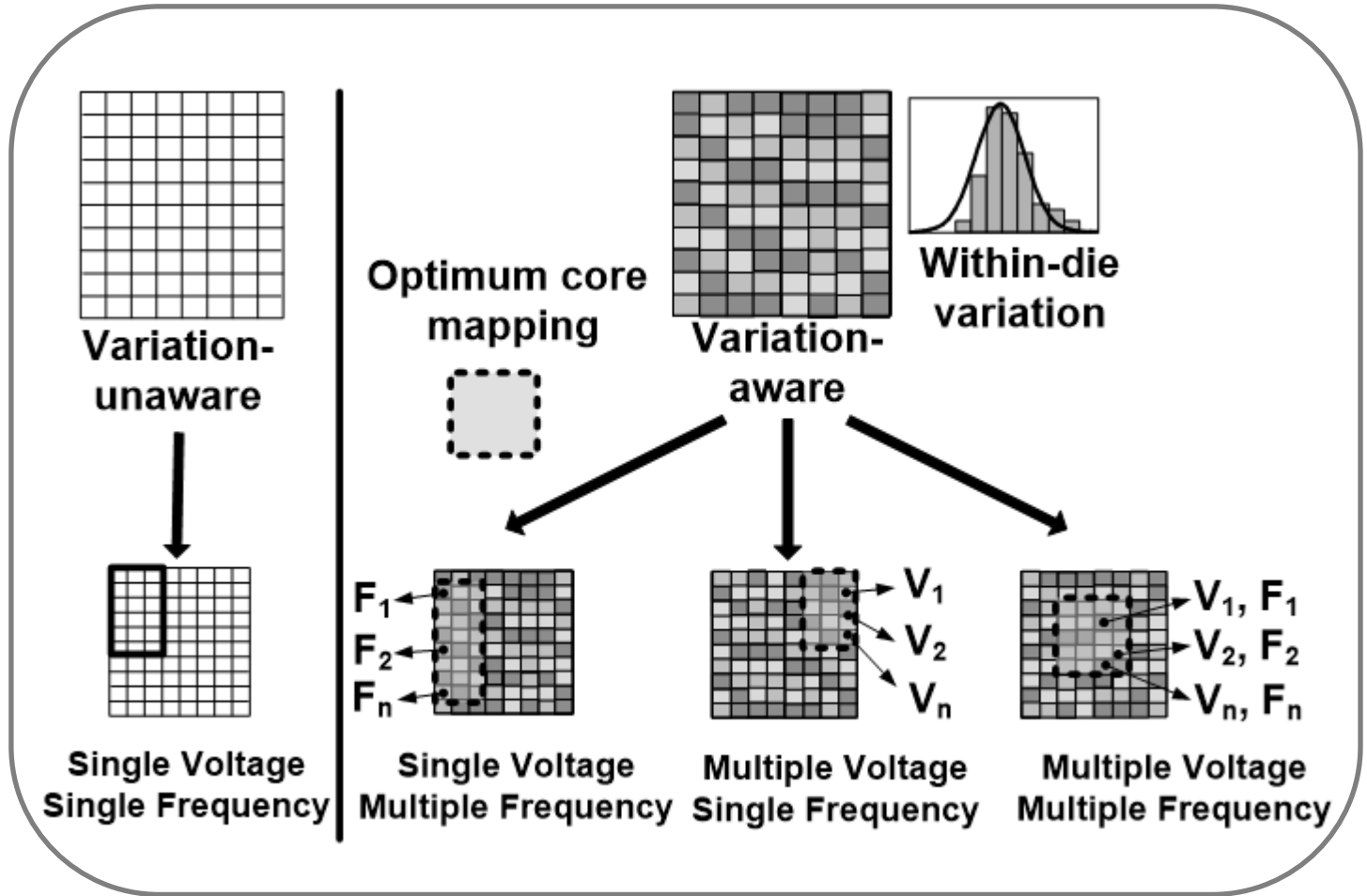
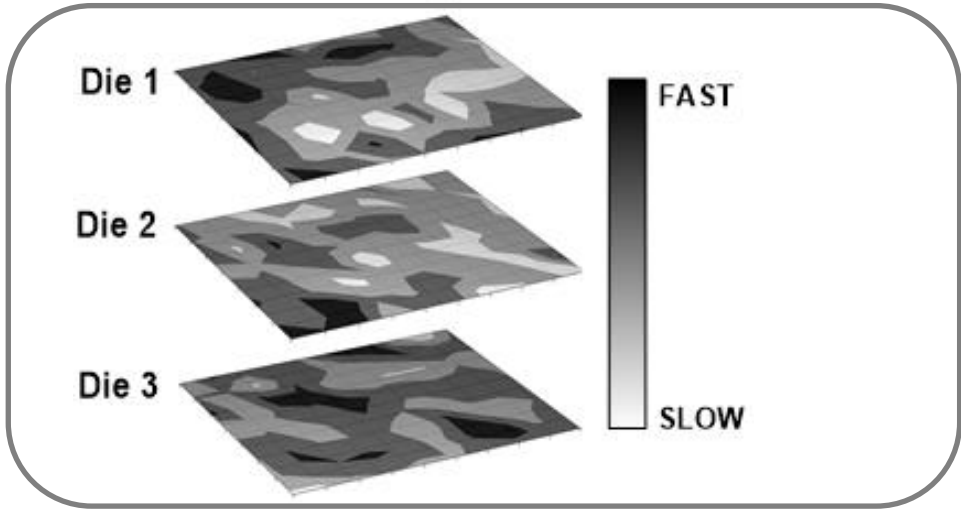
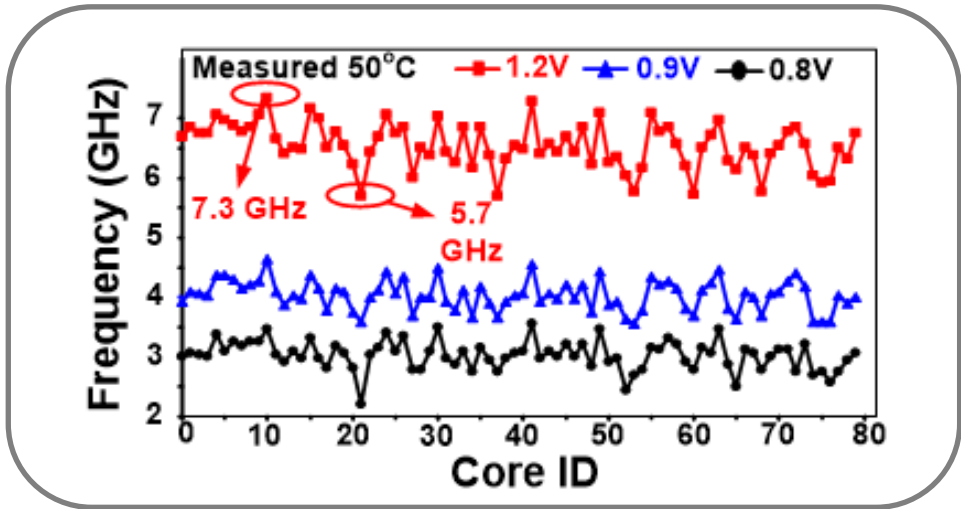


Self-Powered cm-Scale Integrated Platforms



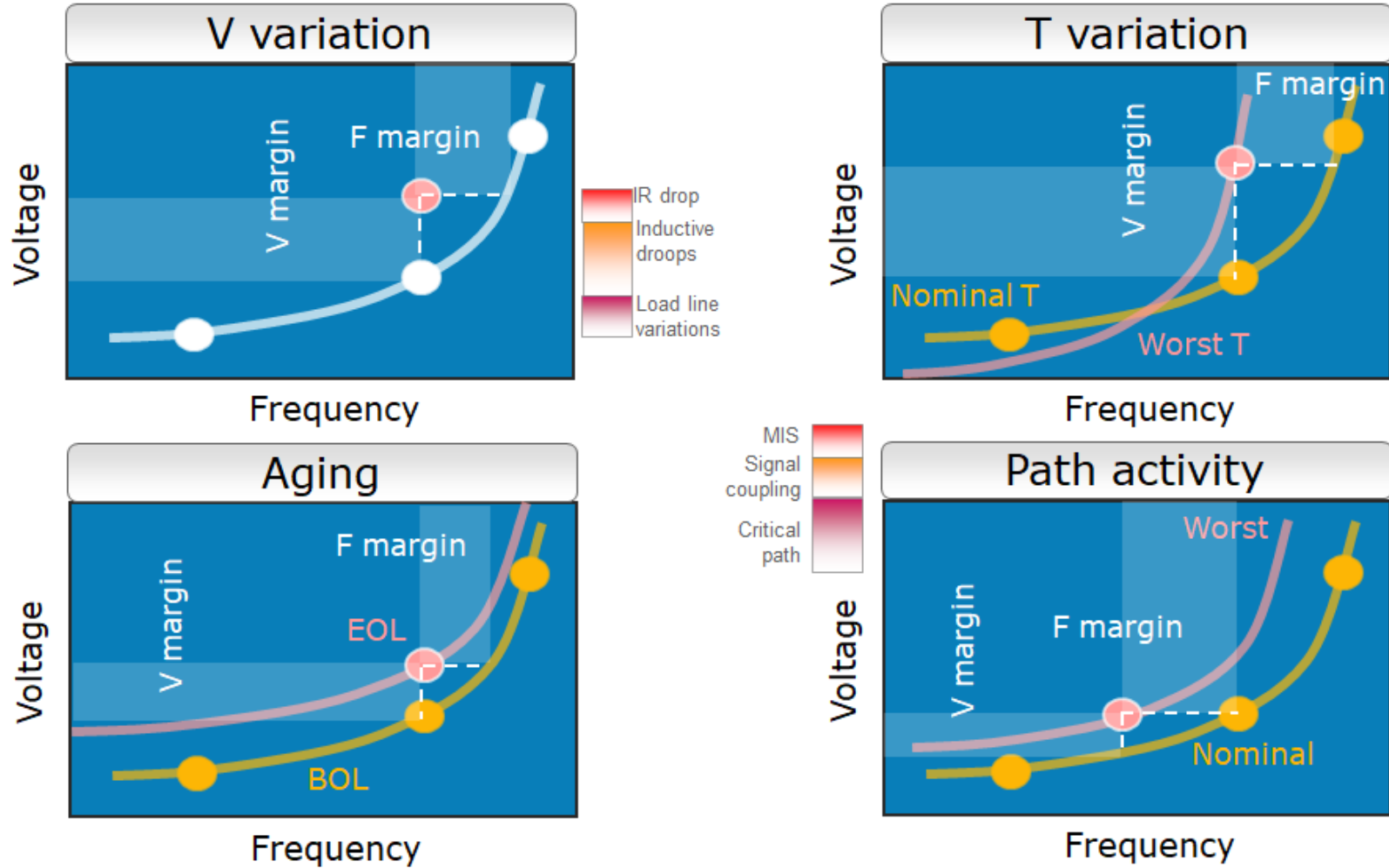
* T. Karnik, et al., 2018 ISSCC

Variation-Aware SoC Design & Operation

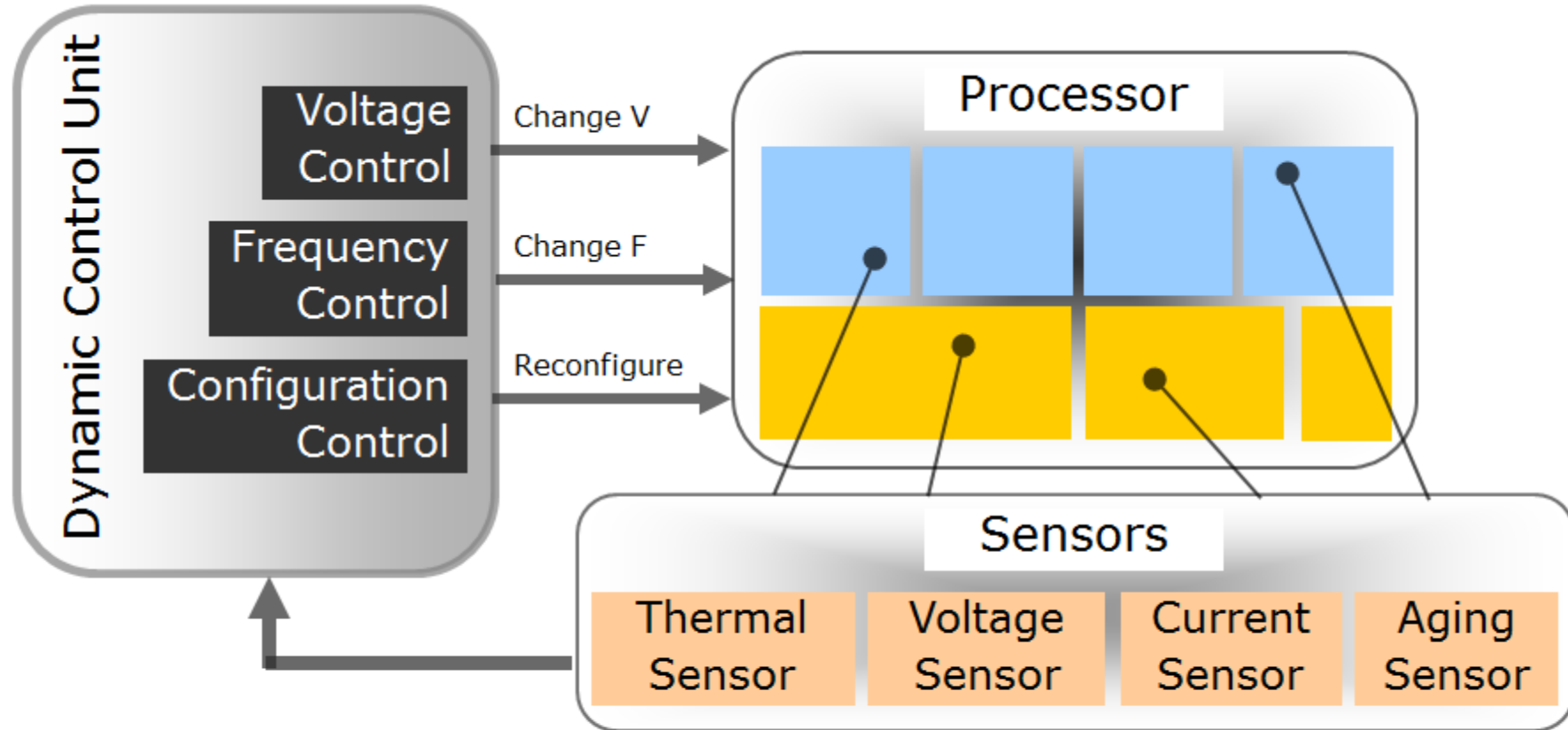


* S. Dighe, et al., JSSC, Jan 2011

Voltage-Frequency Margins



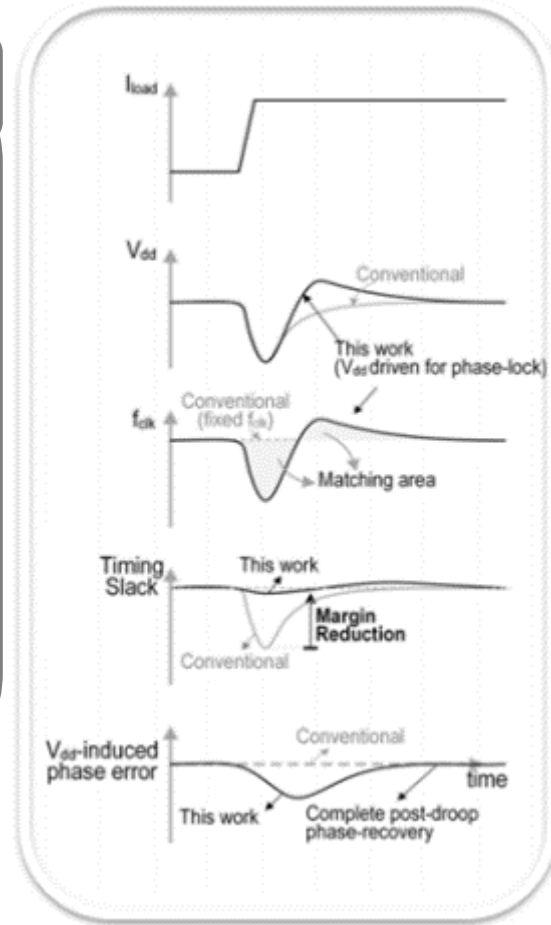
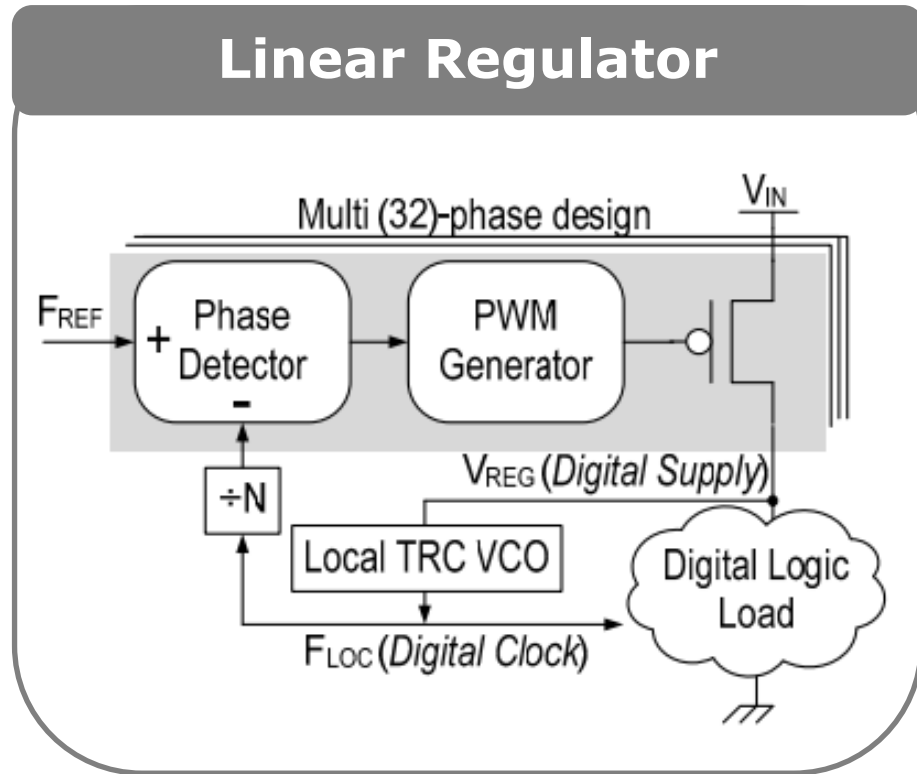
Runtime Self-Adaptation



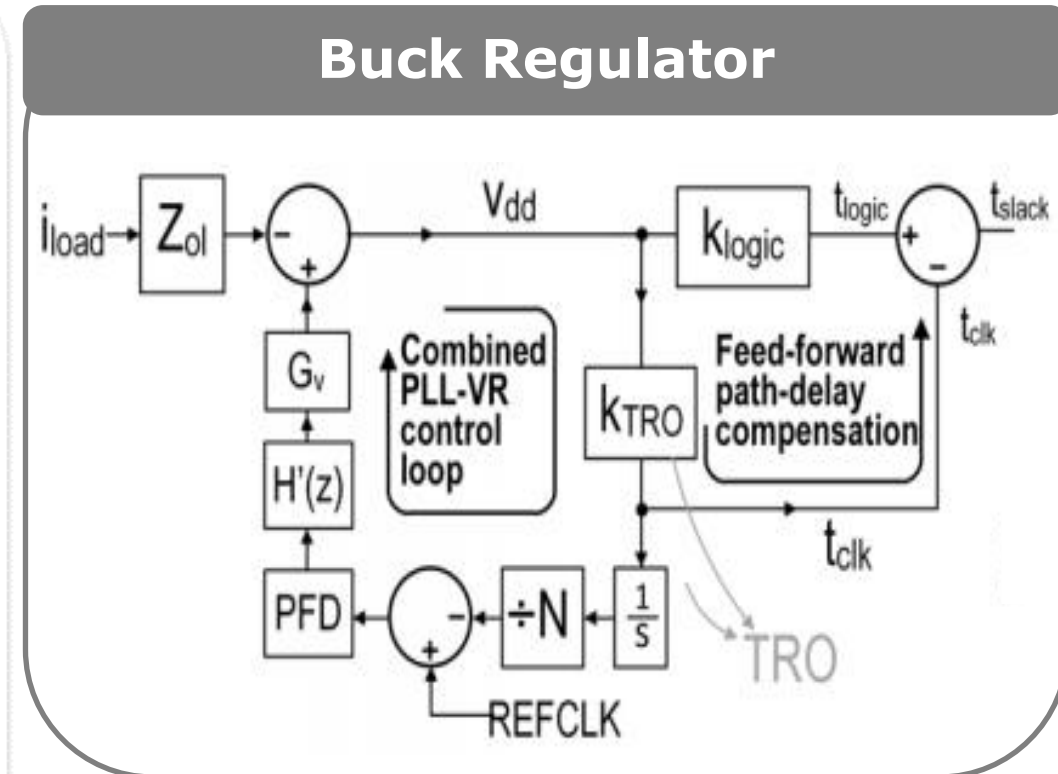
Adapt & reconfigure for best power-performance

Unified Voltage-Frequency Regulation

Linear Regulator



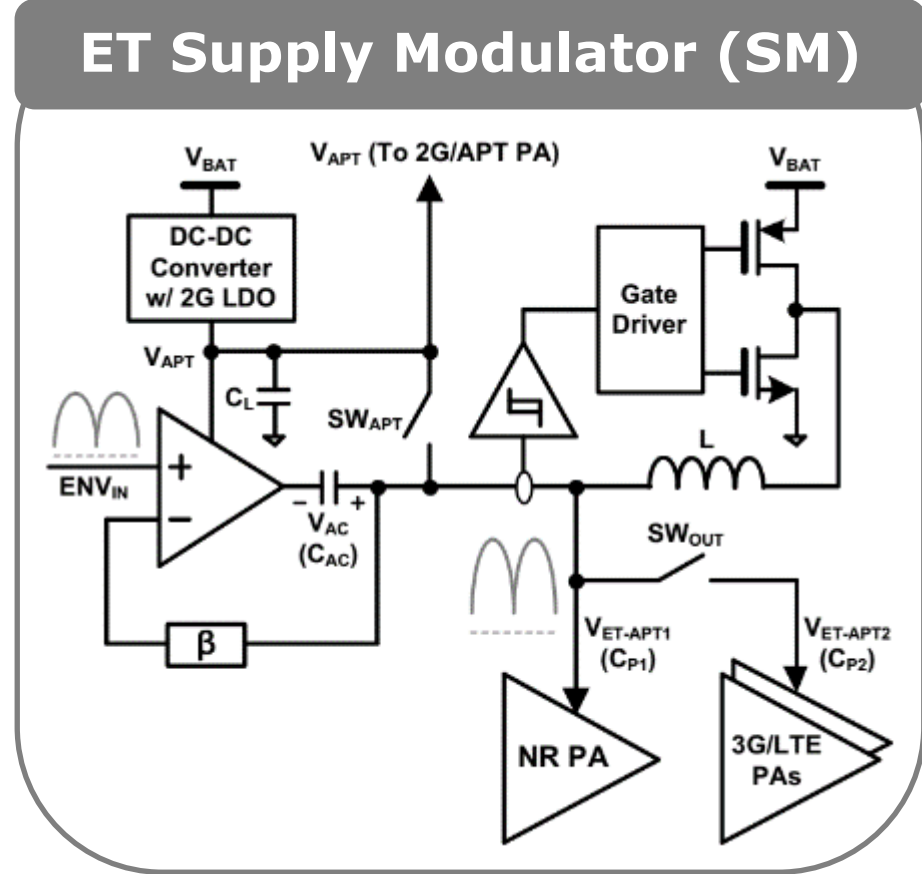
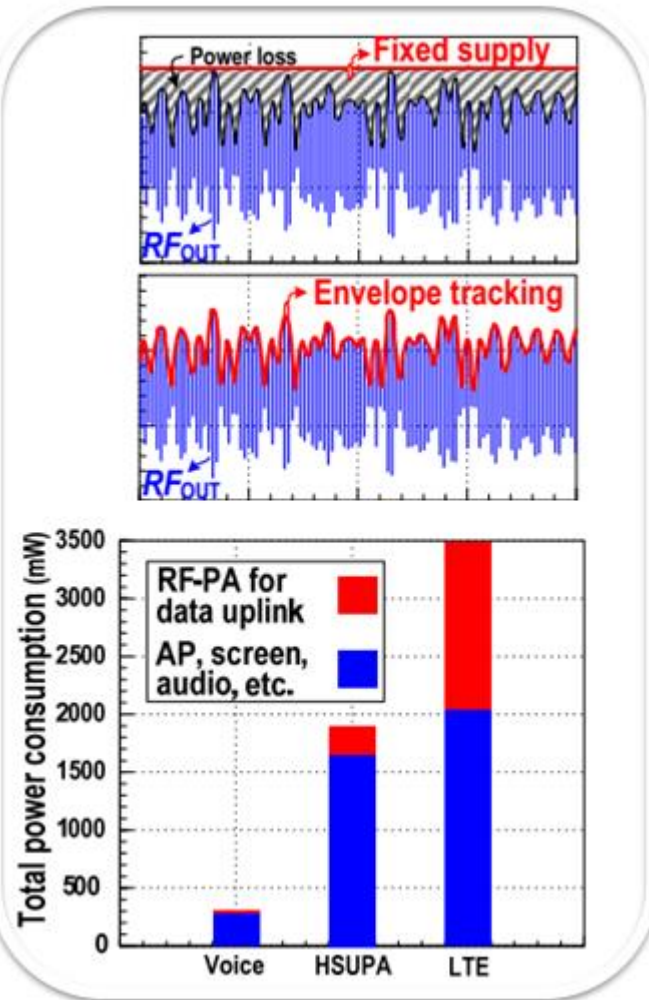
Buck Regulator



* S. Gangopadhyay, et al., 2016 ESSCIRC

* X. Sun, et al., 2018 ISSCC

Envelop Tracking (ET) RF Power Amplifiers (PA)



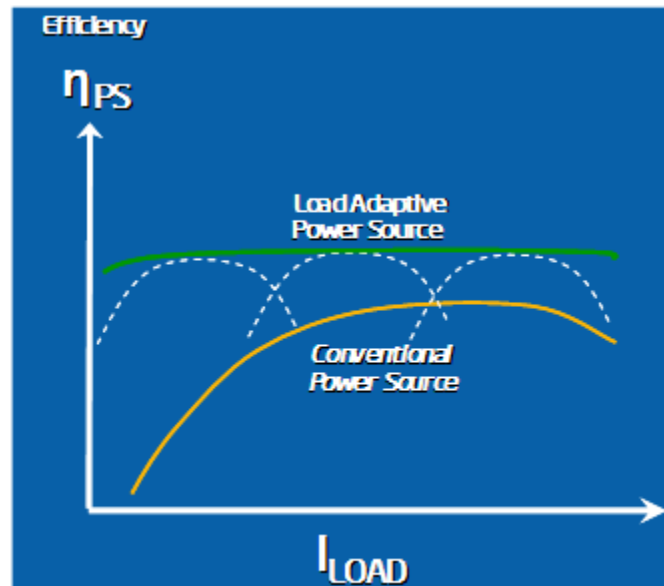
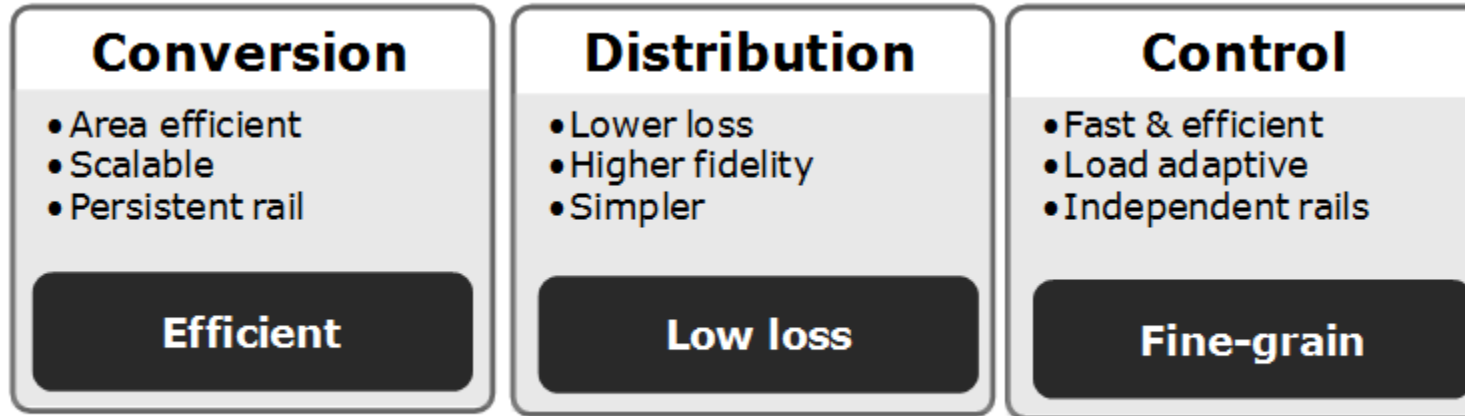
Communication system		PAPR (dB)	Bandwidth (MHz)
2G	GSM	0	
2.5G	EDGE	3.2	0.2
3G	CDMA2000	3.5 ~ 9	1.25
	TD-SCDMA		1.6
4G	LTE	8.5 ~ 13	2.4 ~ 20

Protocol/ Bandwidth	Avg. ET-SM output power	ET-SM efficiency
LTE 20MHz	1.92W	72-85%
WLAN 10MHz	0.594W	65%
LTE 20MHz	1.53W*	78-83%
LTE 10MHz	0.93W	82% (Peak)
HSUPA 5MHz	0.5W*	60%-80%
LTE 20MHz	0.82W*	83% (Peak)
LTE 10MHz	0.5W*	70% (At least)
LTE 40MHz	0.54W*	64%-83%

100Mhz bandwidth & faster power tracking for 5G

Voltage Regulators for Integrated Platforms

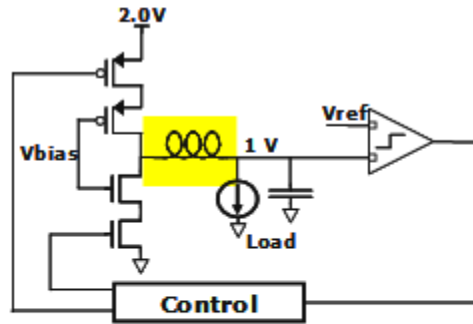
Voltage Regulator (VR) Challenges



Integrated Voltage Regulators (IVR)

LCVR

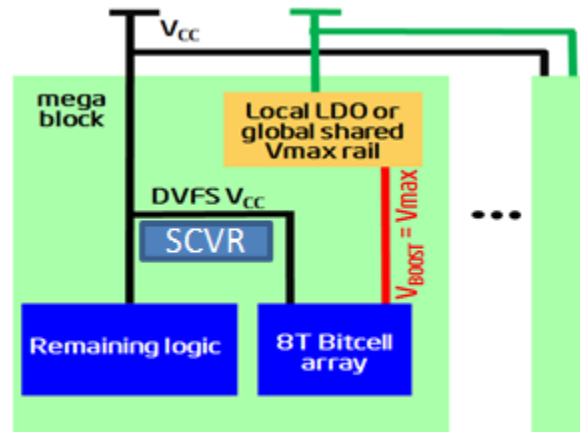
- High efficiency
- Off-die inductor
- Continuous V_{out}
- Large domains
- Fast response



Off-die inductors
All circuits on die

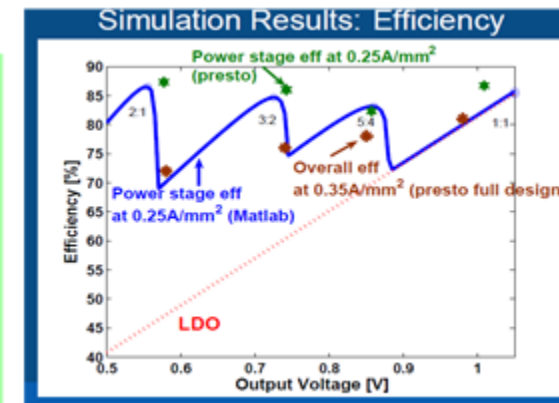
SCVR

- High efficiency
- Die integration
- Discrete V_{out}
- Finer domains
- Faster response

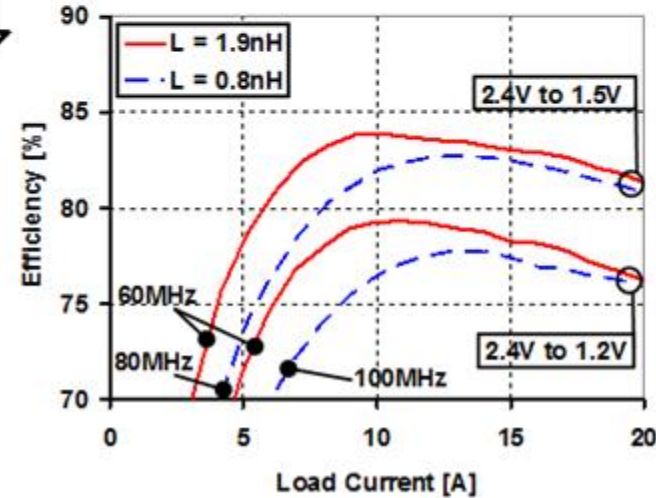
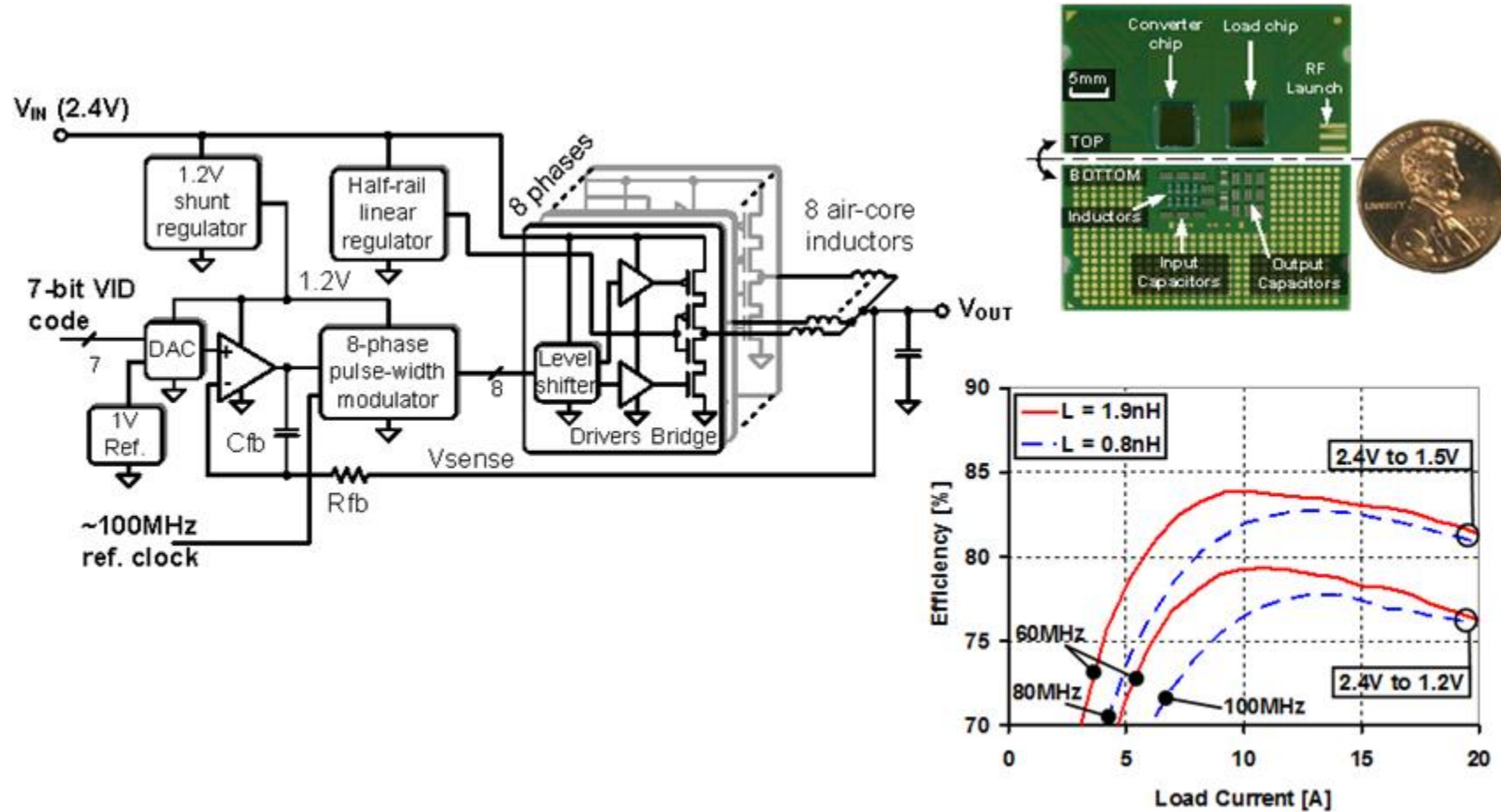


LDO

- Low efficiency
- Die integration
- Narrow V_{out} range
- Finest domains
- Fastest response

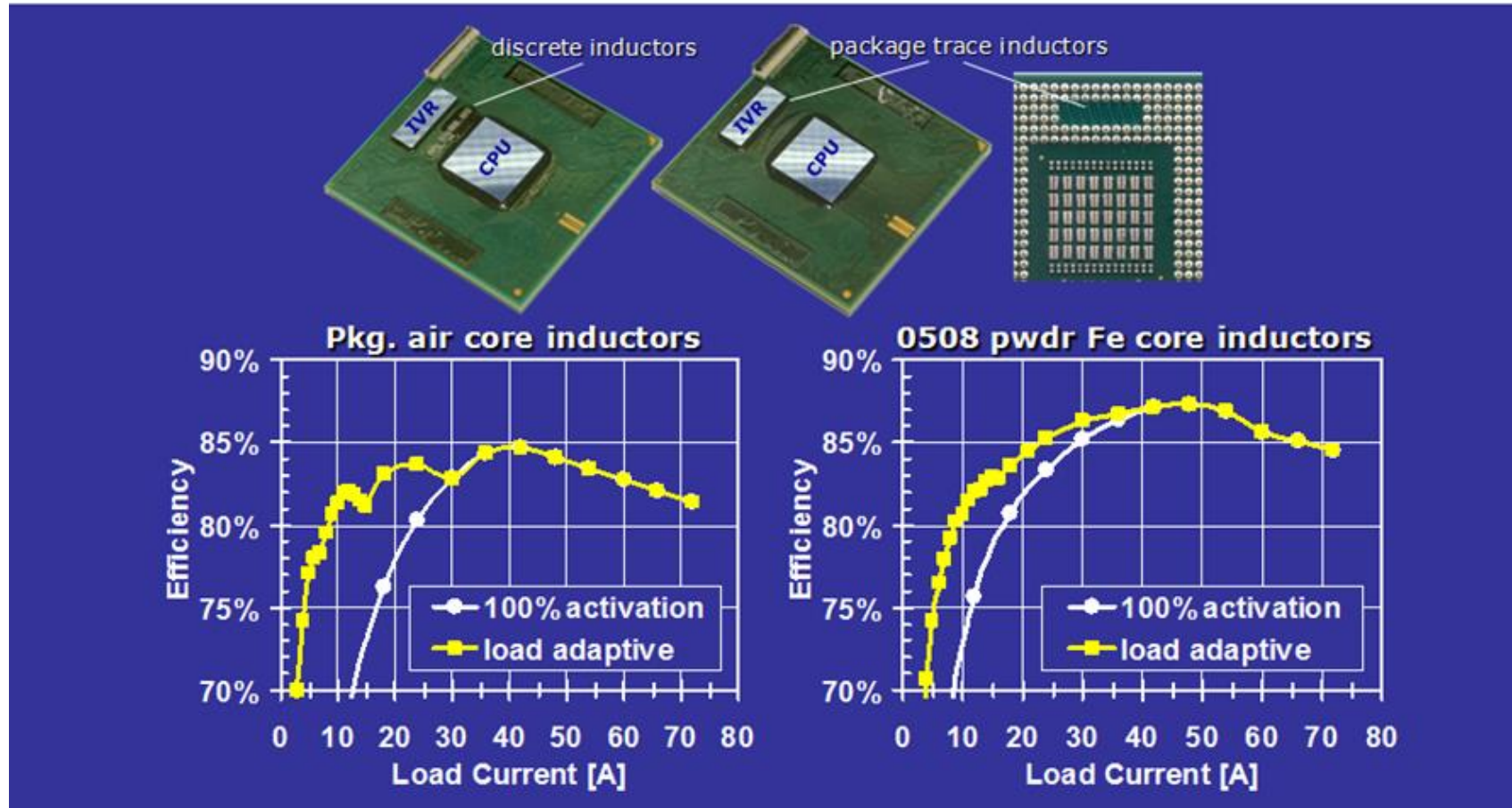


Integrated High-Frequency LCVR



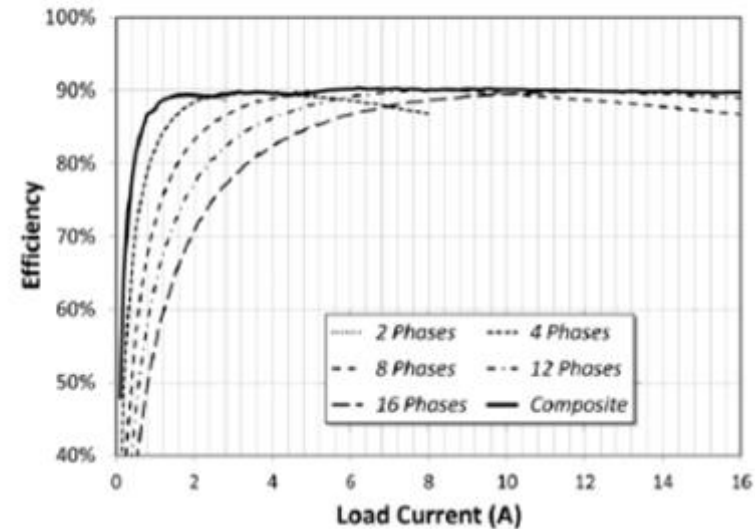
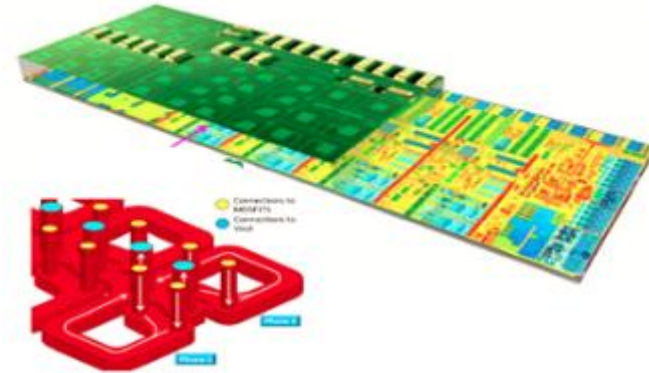
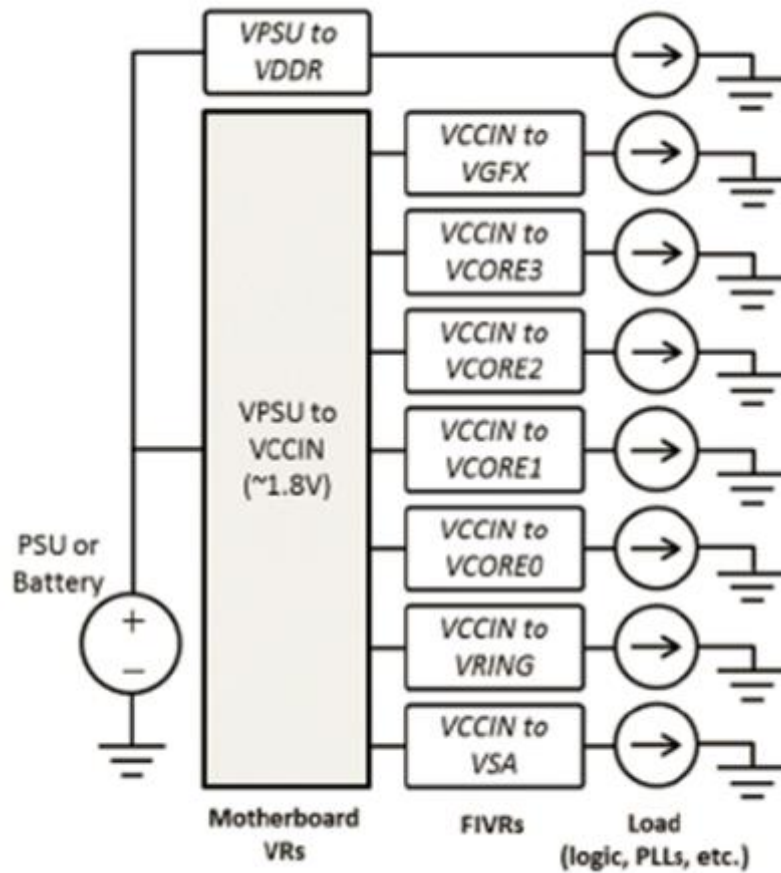
* G. Schrom, et al., 2007 APEC

Package-Integrated LCVR



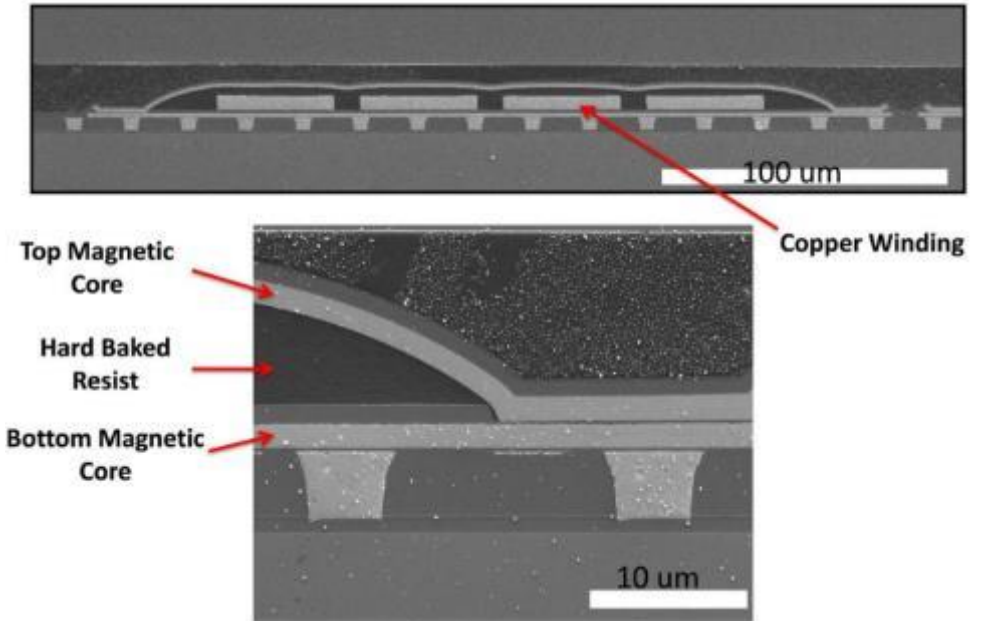
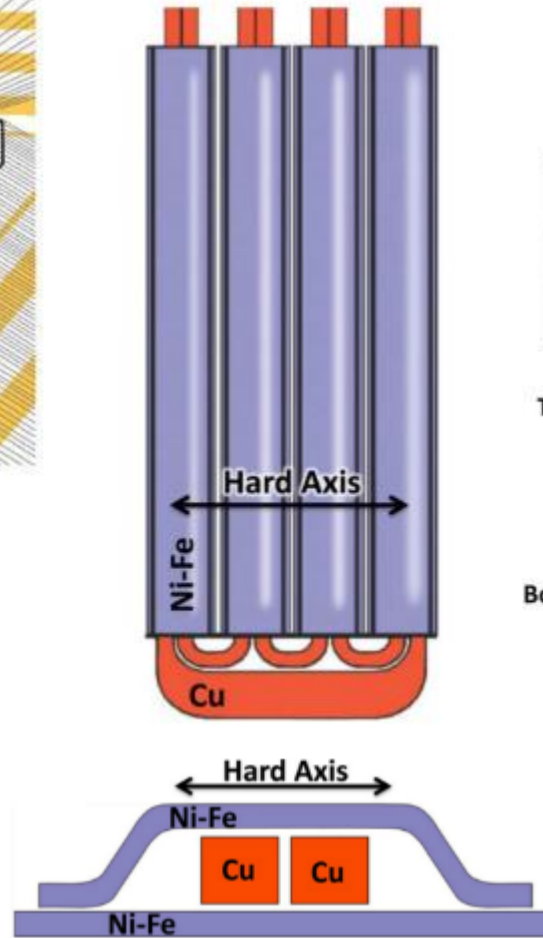
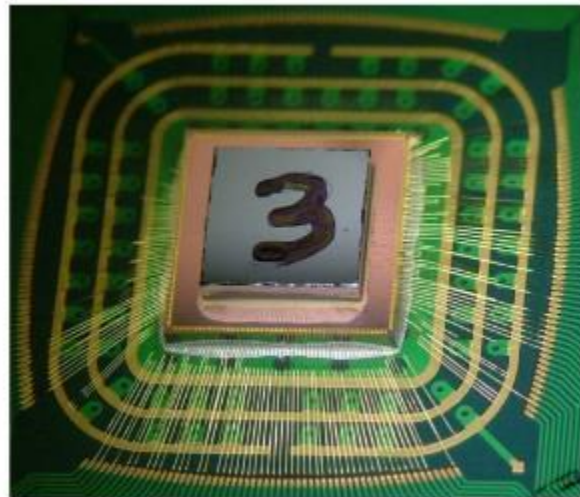
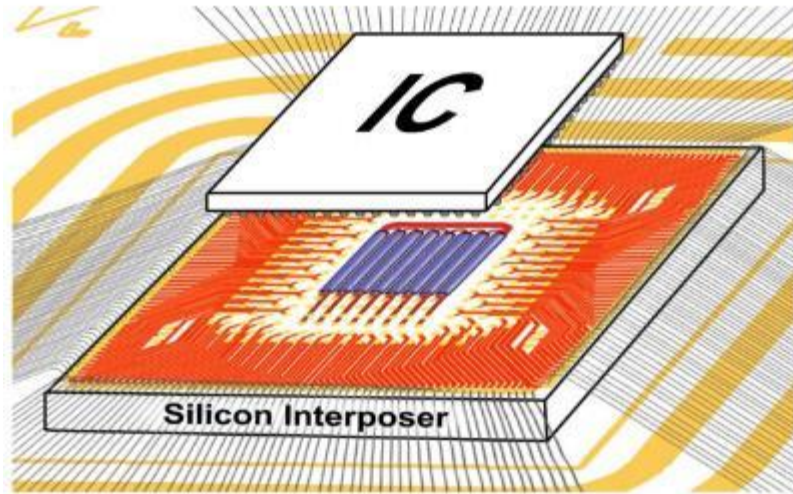
* G. Schrom, et al., 2010 APEC

FIVR with In-Package Air-Core Inductors



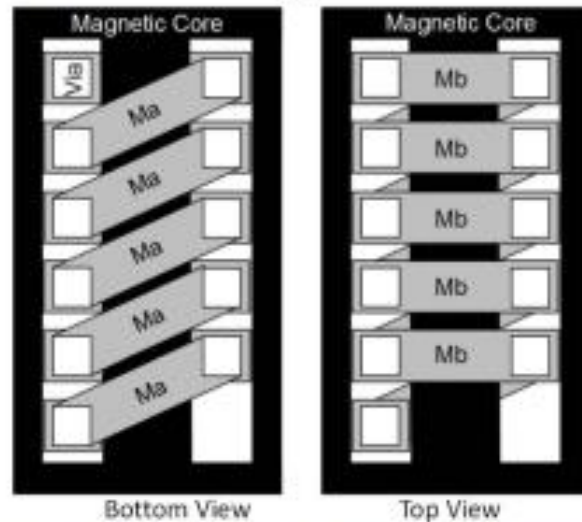
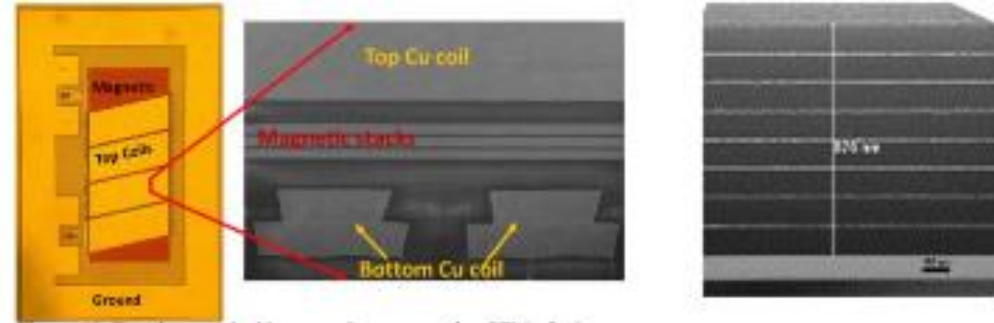
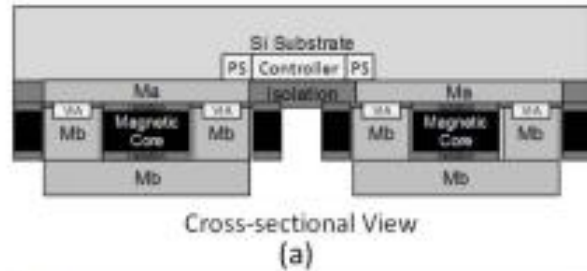
* E. A. Burton, et al., 2014 APEC

2.5D-IVR with Magnetic-Core Inductors

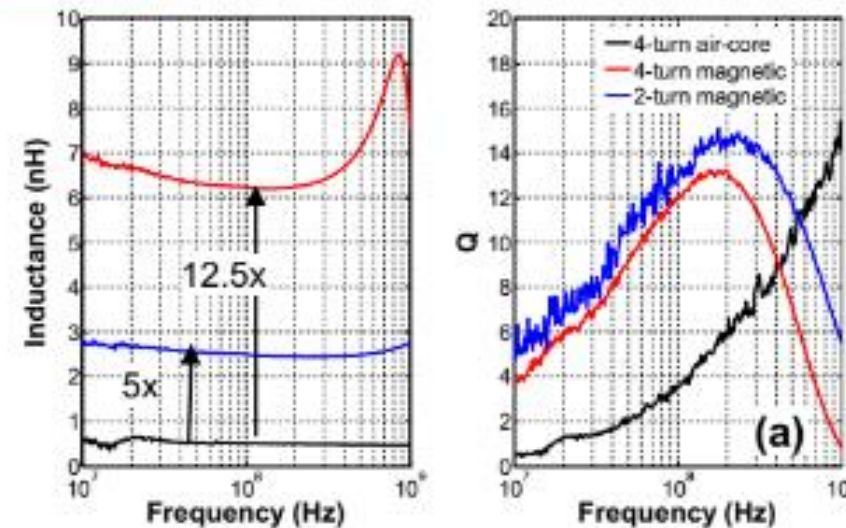


* N. Sturcken, et al., JSSC, Jan 2013

On-Die Solenoid Inductor with Planar Magnetics



1A/mm², 1.5nH, 3.5Q @100MHz



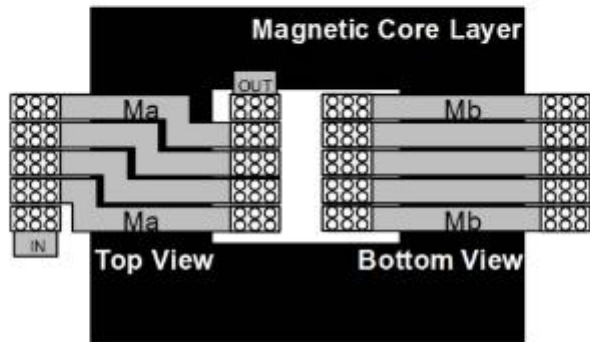
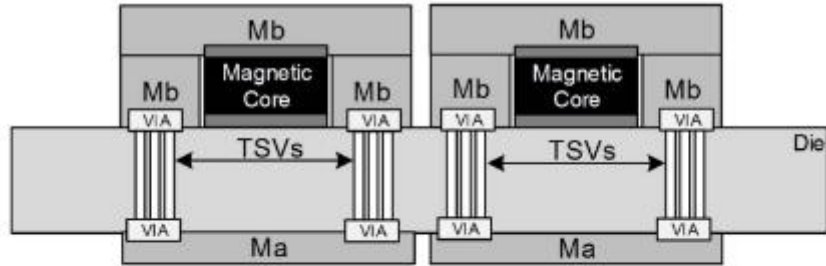
2nH, 17Q @100MHz

* H. K. Krishnamurthy, et al., JSSC, Jan 2018

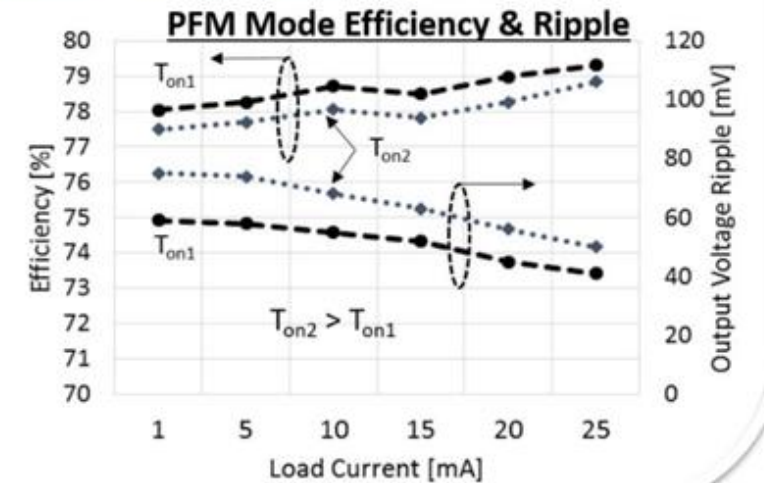
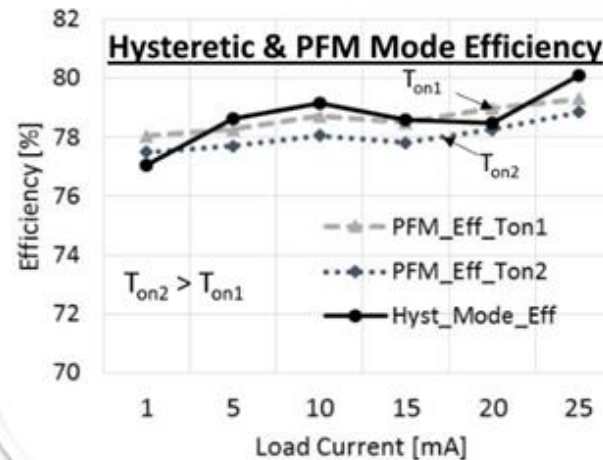
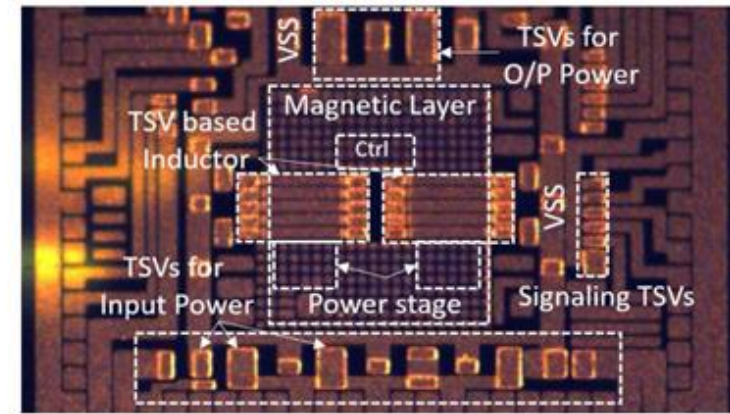
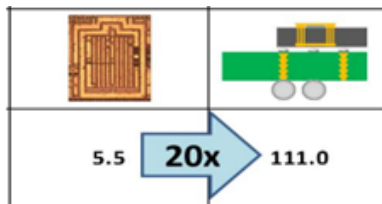
* N. Wang, et al., 2016 IEDM

3D-Integrated LCVR

3D-TSV Inductor



Inductance density
(nH/mm²)



* H. K. Krishnamurthy, et al., JSSC, Apr 2018

Summary

- Future “smart & connected” systems demand uncompromising performance with maximum energy efficiency in compact form factors

- Integrated platforms across IoE edge-network-cloud need
 - fine-grain multi-voltage SoC design
 - fast & efficient wide-range DVFS
 - efficient power delivery & energy harvesting
 - self-adaptation to variations

- Monolithic & heterogeneous 2.5D/3D-integrated *efficient, fast & compact* power converters, voltage regulators and supply modulators are essential for smart system-level power management & adaptation